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Dated: May 18, 2004

Signature: 

(Daryl K. Neff)

Docket No.: TESSERA 3.0-306 II CIP I
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Warner et al.

Serial No.: 10/783,314

Group Art Unit: N/A

Filed: February 20, 2004

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SUBMISSION OF FORMAL DRAWINGS

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Enclosed herewith are fifteen sheets of formal drawings for filing in connection with the above-identified patent application.

In the event there are any fees due or owing in connection with this matter, please charge same to our Deposit Account No. 12-1095.

Dated: May 18, 2004

Respectfully submitted,

By 

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